



PROPOSED STACK-UP

Texas Instruments

TRF3703 Rev A (Impedance Model)

<u>Overall Thickness =</u>		.062	+/- .006		Polyclad 370 HR	(Lead Free Assembly)
					Er (Dielectric Constant) = 4.3	
	<u>Dielectric</u>		<u>Copper</u>	<u>Target Impedance</u>	<u>Line Width</u>	<u>Calc</u>
1	----- .011	Signal	1.5 oz	50 ohms +/- 10%	.018	50.3
2	----- .033	Plane	1 oz			
3	----- .011	Plane	1 oz			
4	-----	Plane	1.5 oz			
	.062	Final Thickness (After Plating)				

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Important:

- 1) Approval of this stack-up supersedes fabrication drawing requirements.**
 - 2) Some laminates require special order and additional lead time.**
- Please check with MEI sales personnel and verify material availability.**